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Advance Product Change Notification	201606013A

Issue Date: 07-Jul-2016

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QUALITY

Change Category

[X] Wafer Fab Process	[ ] Assembly Process	[ ] Product Marking	[ ] Test Location	[ ] Design
[X] Wafer Fab Materials	[ ] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage

Release of 8 inch wafer diameter for general purpose diodes

Details of this Planned Change

Release of production using 8 inch wafer diameter for general purpose diodes in SOD323 (SC-76) and SOT23 packages. In addition a 2nd source epitaxy supplier will be introduced. The top metallization thickness of the affected diodes will be adapted.

Old products: Production using 6 inch wafer diameter, inhouse epitaxy, top side metallization thickness 1.4µm
Changed products: Production using 8 inch wafer diameter, inhouse epitaxy or external epitaxy supplier, top side metallization thickness 1.5µm

Production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.
Why do we Plan this Change
To increase flexibility and volume ramp-up.
Identification of Affected Products
The 8 inch products can be identified by a marker on the die surface.

Product Availability

Sample Information
Samples are available upon request
Samples can be ordered now and will be shipped latest with FPCN issue date.

Impact

No impact to the products' functionality anticipated.
Disposition of Old Products
Existing inventory will be shipped until depleted

Timing and Logistics

The Self Qualification Report will be ready on 06-Aug-2016.
The Final PCN is planned to be issued on: 06-Aug-2016.
Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 06-Aug-2016.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:
Name   GA Customer Support
e-mail address   DiscrQA.Helpdesk.GA-Products@nxp.com
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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Affected Parts

BAS19,215
BAV23C,215
BAS20,215
BAS20,215
BAS21,215
BAS21,215
BAS21,235
BAS21,235
BAV23S,215
BAV23S,215
BAS321,115
BAS321,115
BAV23A,215
BAV23A,215
BAV23C,215
BAS19,215